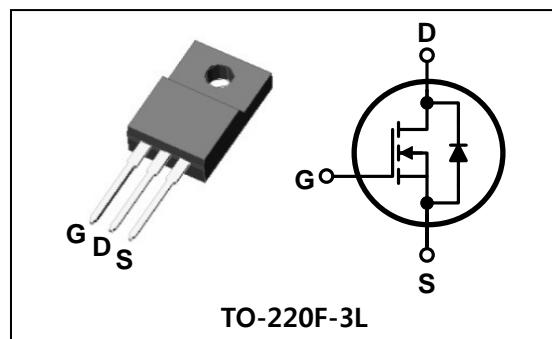


SWITCHING REGULATOR APPLICATIONS

Features

- High Voltage : $BV_{DSS}=650V$ (Min.)
- Low C_{rss} : $C_{rss}=13pF$ (Typ.)
- Low gate charge : $Q_g=45nC$ (Typ.)
- Low $R_{DS(on)}$: $R_{DS(on)}=0.9\Omega$ (Max.)

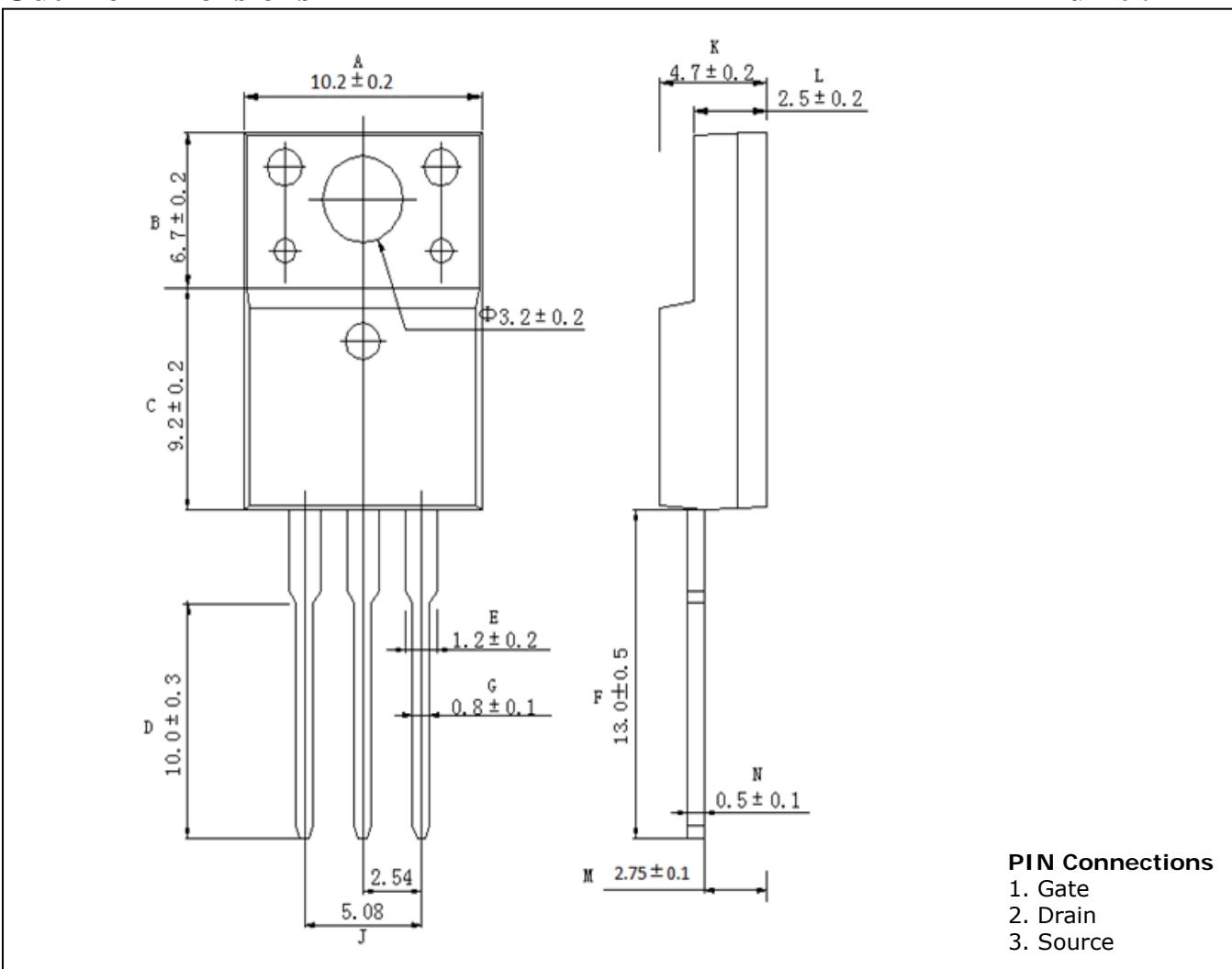
PIN Connection



Ordering Information

Type NO.	Marking	Package Code
MF10N65	MF10N65	TO-220F-3L

Outline Dimensions



Absolute maximum ratings ($T_C=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	650	V
Gate-source voltage	V_{GSS}	± 30	V
Drain current (DC) *	I_D	$T_C=25^\circ\text{C}$	10
		$T_C=100^\circ\text{C}$	5.5
Drain current (Pulsed) *	I_{DM}	40	A
Power dissipation	P_D	50	W
Avalanche current (Single) ②	I_{AS}	10	A
Single pulsed avalanche energy ②	E_{AS}	480	mJ
Avalanche current (Repetitive) ①	I_{AR}	10	A
Repetitive avalanche energy ①	E_{AR}	11.6	mJ
Junction temperature	T_J	150	$^\circ\text{C}$
Storage temperature range	T_{stg}	-55~150	

* Limited by maximum junction temperature

Characteristic	Symbol	Typ.	Max.	Unit
Thermal resistance	$R_{th(J-C)}$	-	2.5	$^\circ\text{C}/\text{W}$
	$R_{th(J-A)}$	-	62.5	

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV_{DSS}	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	650		-	-
Gate threshold voltage	$V_{GS(\text{th})}$	$I_D=250\mu\text{A}, V_{DS}=V_{GS}$	2.0	-	4.0	V
Drain-source cut-off current	I_{DSS}	$V_{DS}=650\text{V}, V_{GS}=0\text{V}$	-	-	1	μA
Gate leakage current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 30\text{V}$	-	-	± 100	nA
Drain-source on-resistance ^(④)	$R_{DS(\text{on})}$	$V_{GS}=10\text{V}, I_D=5.0\text{A}$	-	0.75	0.9	Ω
Forward transfer conductance ^(④)	g_{fs}	$V_{DS}=10\text{V}, I_D=5.0\text{A}$	-	8.0	-	S
Input capacitance	C_{iss}	$V_{GS}=0\text{V}, V_{DS}=25\text{V}$ $f=1\text{ MHz}$	-	1600	2350	pF
Output capacitance	C_{oss}		-	110	160	
Reverse transfer capacitance	C_{rss}		-	13	18	
Turn-on delay time	$t_{d(\text{on})}$	$V_{DD}=300\text{V}, I_D=10\text{A}$ $R_G=25\Omega$	-	23	-	ns
Rise time	t_r		-	69	-	
Turn-off delay time	$t_{d(\text{off})}$		-	144	-	
Fall time	t_f		-	77	-	
Total gate charge	Q_g	$V_{DS}=480\text{V}, V_{GS}=10\text{V}$ $I_D=10\text{A}$	-	45	-	nC
Gate-source charge	Q_{gs}		-	7.5	-	
Gate-drain charge	Q_{gd}		-	18.5	-	

Source-Drain Diode Ratings and Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Source current (DC)	I_S	Integral reverse diode in the MOSFET	-	-	10	A
Source current (Pulsed) ^(①)	I_{SM}		-	-	40	
Forward voltage ^(④)	V_{SD}	$V_{GS}=0\text{V}, I_S=10\text{A}$	-	-	1.4	V
Reverse recovery time	t_{rr}	$I_S=10\text{A}, V_{GS}=0\text{V}$ $dI_F/dt=100\text{A}/\mu\text{s}$	-	420	-	ns
Reverse recovery charge	Q_{rr}		-	4.2	-	uC

Note :

- ① Repetitive rating : Pulse width limited by maximum junction temperature
- ② $L=10\text{mH}, I_{AS}=10\text{A}, V_{DD}=50\text{V}, R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$
- ③ Pulse Test : Pulse width $\leq 300\text{us}$, Duty cycle $\leq 2\%$
- ④ Essentially independent of operating temperature

Fig. 11 Gate Charge Test Circuit & Waveform

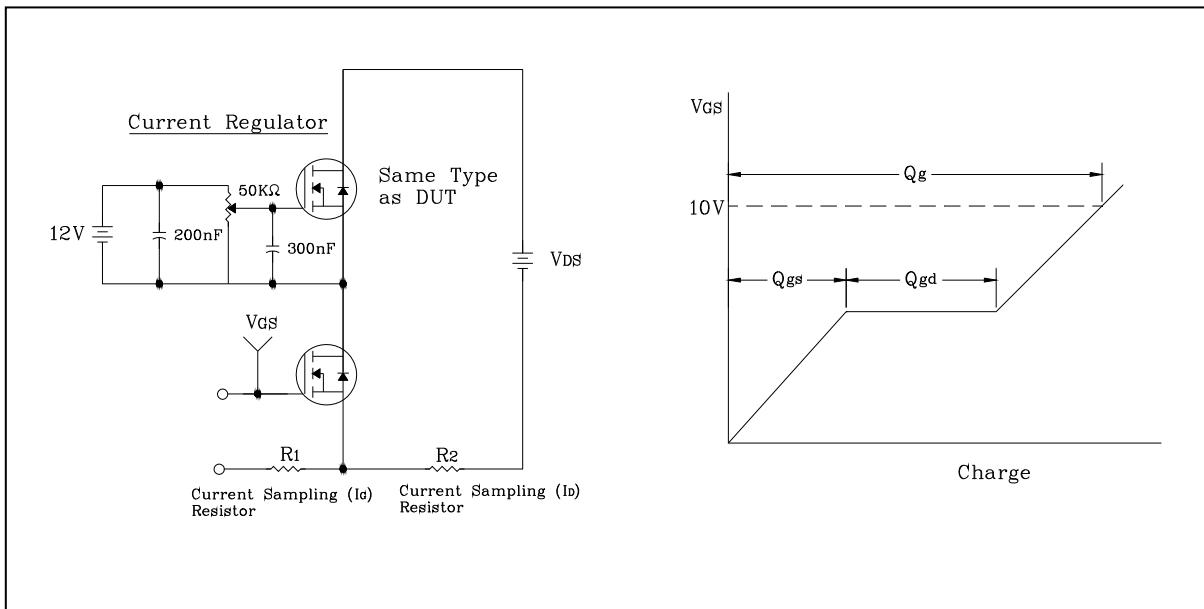


Fig. 12 Resistive Switching Test Circuit & Waveform

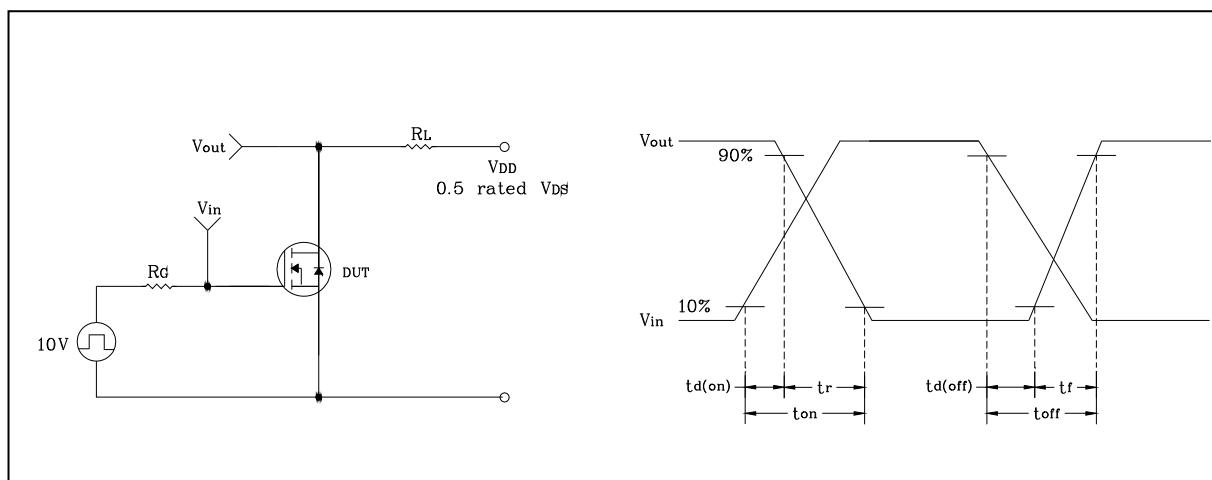


Fig. 13 E_{AS} Test Circuit & Waveform

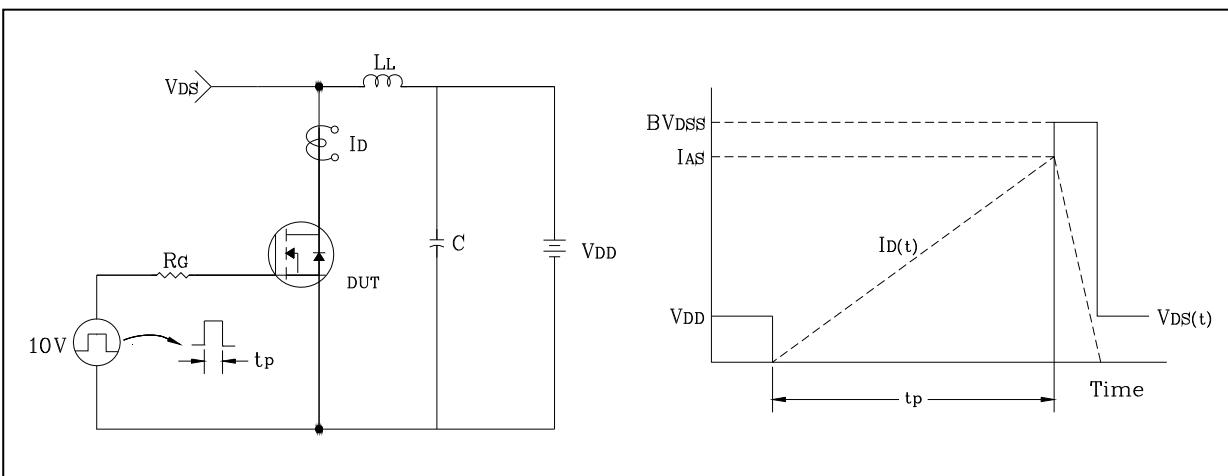


Fig. 14 Diode Reverse Recovery Time Test Circuit & Waveform

